

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	bonding adj pad and spacing adj pad and passivation adj layer and chip	USPAT; EPO; JPO; DERWENT	OR	OFF	2005/05/24 15:32
L2	1	bonding adj pad and passivation adj layer and chip and metallic adj bump adj pad	USPAT; EPO; JPO; DERWENT	OR	OFF	2005/05/24 15:36
L3	31	bonding adj pad and passivation adj layer and chip and metallic near5 pad	USPAT; EPO; JPO; DERWENT	OR	OFF	2005/05/24 15:36